

ABSTRACT OF THE DISCLOSURE

A soldered assembly for a microelectronic element includes a microelectronic element, solder columns extending from a surface of the microelectronic element and terminals connected to distal ends of the columns. The assembly can be handled and mounted using conventional surface-mount techniques, but provides thermal fatigue resistance. The solder columns may be inclined relative to the chip surface, and may contain long, columnar inclusions preferentially oriented along the lengthwise axes of the columns.

309501_1.DOC

TESSERA 3.0-139 DIV